

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT3494290

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	RAN BERMAN	08/17/2015
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State/Country:	ISRAEL	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	14810488
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ATTORNEY DOCKET NUMBER:	1444-B-01-US	
NAME OF SUBMITTER:	EITAN WAKS	
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DATE SIGNED:	08/23/2015	
Total Attachments: 1		
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Assignment
Docket No. BRS_00024_US
Title: "METHOD AND SYSTEM FOR FABRICATION OF CUSTOM-MADE MOLDS AND CONCRETE - ARCHITECTURAL COMPONENTS"
U.S. Application No. 14/810,488

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, the undersigned:

Address	Inventor
14 Hatchia Street Tel Aviv, 6816914 Israel	BERMAN Ran

hereby sell(s), assign(s) and transfer(s) to:

BEYON 3D LTD
14 Hatchia Street
Tel Aviv, 6816914
Israel

(hereinafter called the "Assignee"), its successors, assigns, nominees or other legal representatives, the undersigned's entire rights, title and interest in and to the invention titled:

METHOD AND SYSTEM FOR FABRICATION OF CUSTOM-MADE MOLDS AND CONCRETE - ARCHITECTURAL COMPONENTS

described and claimed in the following Patent Application:

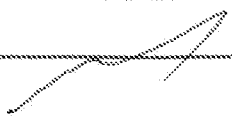
US Patent Application No. 14/810,488, filed on 28 July 2015

and in and to said Patent Application, and all original and reissued Patents granted therefore, and all divisions and continuations thereof, any corresponding PCT Patent Application and the National Phases thereof, including the right to apply and obtain Patents in all other countries, the priority rights under International Conventions, and the Letters Patent which may be granted thereon;

covenant that the undersigned have (has) the full right to convey the entire interest therein assigned;

authorize(s) and request(s) the Registrar of Patents, and any Official of any country whose duty it is to issue Patents on applications as aforesaid, to issue the said Letters Patent to the said Assignee;

and agree(s) to sign all lawful papers, make all rightful oaths, do all lawful acts requisite for such Patent Applications, and do everything possible to aid said Assignee to apply for, obtain and enforce Patent protection for said invention.

ASSIGNOR NAME	SIGNATURE	DATE
BERMAN Ran		17/08/15